



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **I-0404-04** DATE: 4/19/2004

Product Affected: PBGA package (BB416)
(see attachment for affected part #s).

Date Effective: 7/19/2004

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☒ Back Mark Lot Number will have "N1" suffix
☐ Date Code
☐ Other

Contact: Geoffrey Cortes

Title: Manager, Corporate Quality & Reliability

Phone #: (408) 492-8321

Fax #: (408) 727-2328

E-mail: Geoffrey.Cortes@idt.com

Attachment: ☒ Yes ☐ No

Samples: See attachment

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☒ Material IDT has qualified the PBGA package (BB416) using new mold compound Sumitomo EME-G770 series and a new die attach material Ablestik 2300. This notification is to advise our customer of qualification and addition of new assembly materials. The new mold compound and die attach material can meet 260°C peak reflow temperature requirements. Please see attachment for qualification data and additional details.
☐ Testing
☐ Manufacturing Site
☐ Data Sheet
☐ Other

RELIABILITY/QUALIFICATION SUMMARY:

Please see attached reliability qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ **Approval for shipments prior to effective date.**

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____



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ATTACHMENT - PCN #: I-0404-04

PCN Type: Assembly Material Change

Data Sheet Change: None

Detail Of Change: A new mold compound material Sumitomo EME-G770 series and a new die attach material Ablestik 2300 has been qualified for PBGA package (BB416). The successful completion of this qualification has improved IDT's support of current and future production needs for components that meet 260°C peak reflow temperature. There is no change in Moisture Sensitive Level (MSL). Products will be shipped at the existing MSL and each shipment is labeled with the correct MSL. Please refer to the label for MSL information. Customer should not be adversely impacted by this change.

Description	Material	
	Existing	Add
Mold compound material	Nitto HC100XJAA series	Sumitomo EME-G770 series
Die attach material	Ablestik 2000	Ablestik 2300

The affected products are as follow:

Industry Package	IDT Part No	Industry Package	IDT Part No
PBGA 416	IDT79RC32K438-200BB	PBGA 416	IDT79RC32K438-233BBI
PBGA 416	IDT79RC32K438-200BBI	PBGA 416	IDT79RC32K438-266BB
PBGA 416	IDT79RC32K438-233BB	PBGA 416	IDT79RC32K438-300BB

Note: For T & R (shipping method) "8" is added to the part number and for industrial grade, letter "I" is added to the part number.



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ATTACHMENT - PCN #: I-0404-04

Qualification Plan #: P02-11-10

Test Vehicle: IDT72815BG

Qualification Test Plan and Results:

Test Description	Test Method	Test Results BG121 IDT72815BG (SS / # of Fails)
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 100 Hrs)	JESD22-A110-B	45/0
* Temperature Cycling (-55 °C to 125 °C, 1000 cycles)	JESD22-A104-B	45/0
* Auto Clave (121 °C, 2 ATM, 168 Hrs)	JESD22-A102-C	45/0
High Temperature Life Test (1000 Hrs @125 °C or equivalent)	JESD22-A108-B	77/0
High Temp Bake (1000 Hrs @150 °C)	JESD22-A103-B	77/0
Moisture Sensitivity Classification	J-STD-020B	90/0
Internal Visual Inspection	MIL-STD-883, M2010	5/0
External Visual Inspection	JESD22-B101	25/0
X-ray Examination	MIL-STD-883, M2015	45/0
Bond Pull Test	MIL-STD-883, M2011	5/0
Bake & Ball Shear Strength	JESD22-B116	5/0
Physical Dimensions	JESD22-B100-B	5/0
Die Shear Strength	MIL-STD-883, M2019	5/0

Notes: * Test requires moisture pre-conditioning sequence per JESD22-A113C.

SUMITOMO BAKELITE

SUMIKON[®]

EME-G770

MULTI-AROMATIC RESIN
Br/Sb FREE
FOR Pb FREE PKG
LOW WARPAGE

EME-G770

TYPICAL PROPERTIES:

ITEM	TEST METHOD	UNIT	VALUES
SPIRAL FLOW	SB-U-03-003	cm	110
GEL TIME (at 175°C)	SB-U-03-005	sec	32
THERMAL EXPANSION α_1	SB-U-02-002	X 10 ⁻⁵ 1/°C	0.8
THERMAL EXPANSION α_2	SB-U-02-002	X 10 ⁻⁵ 1/°C	3.7
Tg	SB-U-02-002	°C	130
THERMAL CONDUCTIVITY	SB-U-02-004	W/m •°C	96x 10 ⁻²
FLEXURAL STRENGTH	SB-U-01-001	N/ mm ²	
(at 25°C)			170
(at 240°C)			17
FLEXURAL MODULUS	SB-U-01-002	X 10 ² N/mm ²	
(at 25°C)			260
(at 240°C)			6.0
SPECIFIC GRAVITY	SB-U-03-018	-----	2.01
VOLUME RESISTIVITY	SB-U-00-004	Ω - cm	1 x 10 ¹²
(at 150°C)			
UL FLAME CLASS	SB-U-03-003	UL-94	V-0
WATER ABSORPTION	SB-U-03-002	% weight gain	0.15
(boiling, 24 h)			
EXTRACTED Na ⁺	SB-U-04-043	ppm	1
EXTRACTED Cl ⁻	SB-U-04-043	ppm	5

TYPICAL, NOT GUARANTEED PROPERTIES

MOLDING AND POST MOLD CURE CONDITIONS:

	STANDARD	RANGE
TRANSFER PRESSURE	80 x10 ⁵ Pa	70-120 x10 ⁵ Pa
MOLD TEMPERATURE	180°C	175-185°C
CURE TIME (C or A)#	A/90 sec	70-120 sec
POST-MOLD CURE TEMP	175°C	170-180°C
POST-MOLD CURE TIME	6 h	4-8 h

#Conventional or Auto

rev.Feb. '03

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SUMITOMO BAKELITE CO., LTD.

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PILOT TECHNICAL DATA SHEET

ABLEBOND® 2300

ELECTRICALLY CONDUCTIVE ADHESIVE FOR PBGA

DESCRIPTION

Ablebond® 2300 electrically conductive die attach adhesive is designed for Pb-free PBGA and Array BGA packaging. The proprietary hybrid chemistry used in Ablebond® 2300 adhesive has high hot / wet adhesion, low stress and ultra-low moisture absorption allowing packages to withstand the high reflow temperatures necessary

for Pb-free solders (260°C) . It is suitable for die sizes up to 12.7 x 12.7 mm.

Ablebond® 2300 adhesive has also been designed for ease of manufacture with excellent dispensing characteristics, fast cure capability and low bleed on solder mask surfaces.

FEATURES

- Ultra-low moisture absorption
- High hot / wet adhesion
- Low stress
- Fast cure with no voids
- Minimal resin bleed

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Filler Type	Silver	Brookfield CP51 @ 5 rpm Viscosity @ 0.5/Viscosity @ 5 rpm 25% increase in viscosity @ RT	
Viscosity @ 25°C	9,000 cP		ATM-0018
Thixotropic Index	5.9		ATM-0089
Estimated Work Life @ 25°C	> 24 hours		ATM-0087
Estimated Storage Life @ -40°C	6 months		ATM-0068
CURE PROCESS DATA			
Weight loss on cure	1.2%	10 x 10 mm Si die on glass slide	ATM-0031
Recommended Cure Condition	15 minutes @ 175°C		

Typical properties are not intended for use as specification limits. If you need to write a specification, ask for our Standard Release Specification. This is a Pilot product that has been converted to high volume manufacturing and is being monitored for process stability. During this monitoring period, certain properties may be adjusted slightly.

PHYSIOCHEMICAL PROPERTIES- POST CURE			TEST DESCRIPTION	TEST METHOD
Ionics	Chloride	2 ppm	Teflon flask 5 gm sample / 20-40 mesh 50 gm DI water 100°C for 24 hours	ATM-0007
	Sodium	2 ppm		
	Potassium	< 1 ppm		
Weight Loss @ 300°C		1.22%	Thermogravimetric Analysis	ATM-0073
Coefficient of Thermal Expansion			TMA expansion mode	ATM-0055
	Below Tg	60 ppm/°C		
	Above Tg	129 ppm/°C		
Dynamic Tensile Modulus			Dynamic mechanical thermal analysis using < 0.5mm thick sample	ATM-0112
@ 25°C		1800 MPa		
		(260,400 psi)		
@ 250°C		240 MPa		
		(34,350 psi)		
Moisture Absorption @ Saturation		0.22%	Dynamic vapor sorption after 85°C/85% RH exposure	ATM-0093
THERMAL/ELECTRICAL PROPERTIES - POST CURE				
Thermal Conductivity	0.6 W/mK		Laser Flash 4-point probe	ATM-0116 ATM-0020
Volume Resistivity	0.5 ohm-cm			

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ABLEBOND[®] 2300

ELECTRICALLY CONDUCTIVE ADHESIVE FOR PBGA

APPLICATION GUIDELINES

SHIPMENT

This Ablestik product is packed and shipped in dry ice at -80°C. Inside every dry ice shipment of Ablestik's products is a small packet containing the ABLECUBE. This is a small blue cube which retains its shape at -40°C. If the ABLECUBE is exposed to temperatures higher than -40°C, the cube will melt.

Please check the state of the ABLECUBE to ensure the integrity of the shipment. If the ABLECUBE has melted upon Receiving Inspection, place the entire shipment in a -40°C freezer and contact your Ablestik Customer Service or Sales Representative.

UNPACKING

Transfer the syringes from the dry ice to a -40°C freezer without ANY delays. Freeze-thaw voids will form in the syringes if the syringes are repeatedly thawed and refrozen.

STORAGE

This Ablestik product must be stored at -40°C. The shelf life of the material is only valid when the material has been stored at the specified storage condition. Incorrect storage conditions will degrade the performance of the material in both handling (e.g. dispensing or screen printing) and final cured properties.

THAWING

Allow the container to reach room temperature before use. After removing from the freezer, set the syringes to stand vertically while thawing. Refer to Syringe Thaw Time chart on the next page for the thaw time recommendation.

DO NOT open the container before contents reach ambient temperature. Any moisture that collects on the thawed container should be removed prior to opening the container. DO NOT re-freeze. Once thawed to room temperature, the adhesive should not be re-frozen.

ADHESIVE APPLICATION

Thawed adhesive should be immediately placed on dispense equipment for use. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.

Apply enough adhesive to achieve a 25-50 µm (1-2 mil) wet bondline thickness, dispensed with approximately 25% - 50% filleting on all sides of the die. Alternate dispense amounts may be used depending on the application requirements. Star or cross shaped dispense patterns will yield fewer bondline voids than the matrix style of dispense pattern.

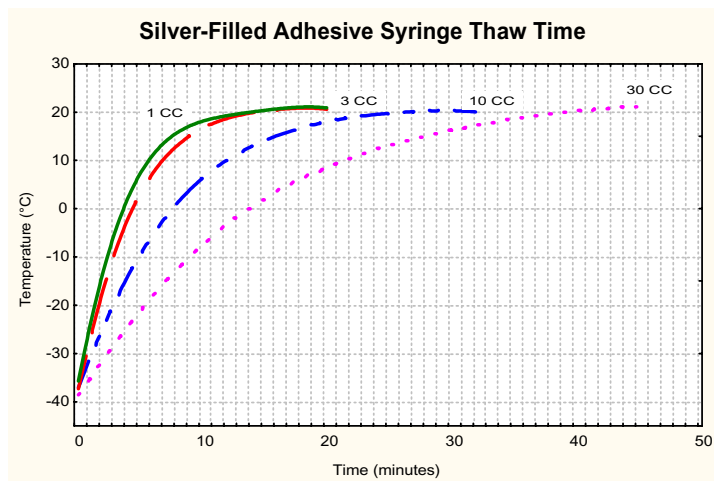
Contact Ablestik Technical Service Department for detailed recommendation on adhesive application, including dispensing.

CURE

Ablebond® 2300 adhesive can be cured in box ovens. See the cure process data on page 1.

AVAILABILITY

Ablebond adhesives are packaged in syringes or jars per customer specification. Available package sizes range from 1cc to 30cc and 1 ounce to 1 pound. For details, refer to the Ablestik Standard Package Data Set or contact your Customer Service Representative.



CAUTION This product may cause skin irritation in sensitive persons. Avoid skin contact. If contact does occur, wash area immediately with soap and water. Please refer to Material Safety Data Sheet (OSHA) for more details.

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